

INFORMATION DISCLOSURE CITATION

(Use several sheets if necessary)

Docket Number (Optional)

PTGF-03070

Application Number

10/747,807

Applicant(s)

Masahiro SHIMADA, et al.

Filing Date

December 30, 2003

Group Art Unit

Not Yet Assigned



U.S. PATENT DOCUMENTS

*EXAMINER INITIAL	REF	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE

FOREIGN PATENT DOCUMENTS

REF	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
						YES	NO

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)

	Kazuhide Abe, et al., "High Reliable Cu Damascene Interconnects with Cu/Ti/TiN/Ti Layered Structure", Oki Technical Review, No. 184, Vol. 67, No. 3, pp. 65-68, October 2000.
	Miki Moriyama, et al., "Future Fabrication Techniques for Cu Wires used in Si ULSI Devices", Material Japan, Vol. 39, No. 11, pp. 901-908 (2000).

EXAMINER

DATE CONSIDERED

8/2/05

EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP Section 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.